

FEATURES

Surface Mounting Design 4.5*3.2*2.7mm

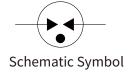
High Current Handling Capability 2000A @ 8/20 μs

Low Capacitance and Insertion Loss

Quick Response and Long Service Life

Moisture sensitivity level: Level 1





APPLICATION INFORMATION

l Communication equipment.
Repeaters, Modems
Telephone Interface,Line cards.
Data communication equipment.

AGENCY APPROVALS

Icon	Solderability		
RoHS	Compliance with 2011/65/EU		
HF	Compliance with IEC61249-2-21:2003		
Pb	Mean lead free		
R .	UL Certificated E505857		

PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated



ELECTRICAL PARAMETER

Parameter	Condition Rating		Unit
DC Blocking Voltage 1)	ng Voltage 1) 100V/s 160-240		V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values ≤ 800	V
impuise Spark-over voltage	At 1kV/μs	Typical values of distribution ≤ 700	V
Impulse Discharge Current 2)	8/20µs	2000	
Insulation Resistance	DC=100V	DC=100V ≥ 1	
Capacitance at 1MHz	$V_{DC}=0.5V$ ≤ 1.0		pF
Operating And Storage Temperature		-40-125	°C

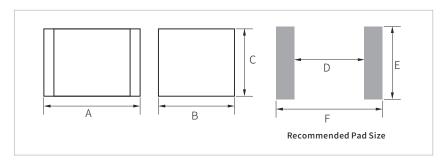
¹⁾ In ionized mode

ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards	
High Temperature Storage Test	Temperature: 85°C; Time:2H	
Low Temperature Storage Test	Temperature: -40°C; Time:2H	
Vibration	Frequency: 10-500Hz ; Amplitude: 0.15mm ; Time: 45min	
Resistance of soldering heat	Temperature: 260±5°C; Time of dip soldering: 10s, 1time	

NOTE:Up-screen program can be specified by customer's request via contacting Semiware service

DIMENSIONS AND RECOMMENDED SOLDERING PAD



Ref.	mm	
A 4.5±0.3mm		
В	3.2±0.3mm	
С	2.7±0.3mm	
D	2.8mm	
E	4.0mm	
F	5.2mm	

²⁾ Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-311 $\,$

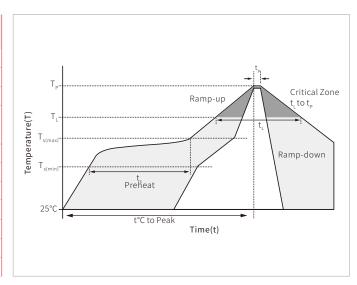


SOLDERABILITY TEST

Solderability		
Solder Pot Temperature	Solder Dwell Time	
245°C ± 5°C	4-6 seconds	

REFLOW PROFILE

Reflow Condition		Lead-free assembly	
	Temperature Min	150°C	
Pre Heat	Temperature Max	200°C	
	Time(min to max)	60 – 180 secs	
Average ra	mp up rate (Liquidus) Temp (T_L) to peak	3°C/second max	
	$T_{s(max)}$ to T_{L} - Ramp-up Rate	5 C/Second max	
Deflam	Temperature (T _L) (Liquidus)	217°C	
Reflow	Time(min to max)(t _s)	60 – 150 seconds	
Peak Temperature (T₅)		260 °C	
Time within 5°C of actual peak Temperature (tp)		20-40 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T♭)		8 minutes max.	
Do not exceed		260°C	



ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
SG4532B200	4.5*3.2*2.7mm	2500PCS	13"



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By QR Code





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